

**Amendments to the Specification:**

Please replace the paragraph under BACKGROUND OF THE INVENTION on page 2 with the following amended paragraph:

Integrated ~~[[circuits]]~~ circuit devices may include several physically separate units, known as dies, that perform separate electrical functions. Dies may be in a stacked configuration on a substrate with a conductive layer within the ~~integrated circuit device~~, in which case the dies are separated by spacers that hold the dies apart. Spacers may be formed using a variety of materials, such as adhesives and silicon. During the process of forming the integrated circuit, spacers and dies may be subject to conditions such as heat and pressure. In some cases, this may result in damage to the integrated circuit.

Please replace paragraph 2 on page 6 with the following amended paragraph:

Dies 102 are components of integrated circuit 100 that perform selected electrical functions. Dies 102 may include silicon, metal, or other conducting or semiconducting material capable of performing one or more desired electrical operations. In a stacked die configuration, dies 102 may be manufactured separately and assembled into a single package. In the depicted embodiment, dies 102 are electrically coupled to a conductive ~~[[plating]]~~ layer on a substrate 112 by wires 114. ~~Conductive plating~~ The conductive layer on the substrate 112 and wires 114 ~~delivery electricity~~ conduct electrical signals for powering dies 102 for their respective operations.

Please replace paragraph 1 on page 8 with the following amended paragraph:

FIGURE 3 illustrates an integrated circuit 200 that reduces the risks associated with making dies 102 and spacers 104 from different materials. In integrated circuit 200, spacers 104 are replaced with multiple spacers 204 (referring to spacers 204A, 204B, ~~[[204C, 204D,]]~~ 204E, and 204F as depicted in Figure 3, and 204A, 204B, 204C and 204D as depicted in Figure 4) of like materials to those of spacers 104. Spacers 204 are arranged in spacer layers. In the embodiment depicted in the top view of die 102A, illustrated in FIGURE 4, spacers 204A, 204B, 204C, and 204D form a square arrangement corresponding to the square shape of die 102A. The depicted square

arrangement corresponding to the square shape of die 102A. The depicted square arrangement is only one of many possible arrangements of spacers 204, and any suitable geometric arrangement that provides a desired level of mechanical stability may also be used. In particular, it may be advantageous to adapt the shape of the arrangement to the shape of die 102.